Low curing temperature SMT adhesive

JU-90-2LTH

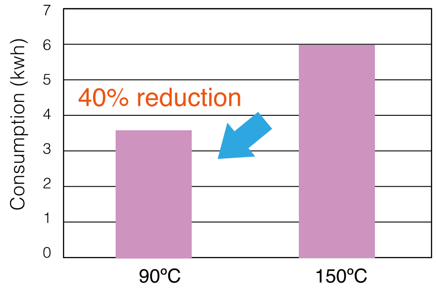
Relieves heat induced stress and saves energy

Advantages of low temperature curing

Advantage - 1

Enables a reduction in running cost of the curing oven and CO_2 emissions by adopting a lower curing temperature of approx. 90°C.

Electricity consumption of curing oven /hr



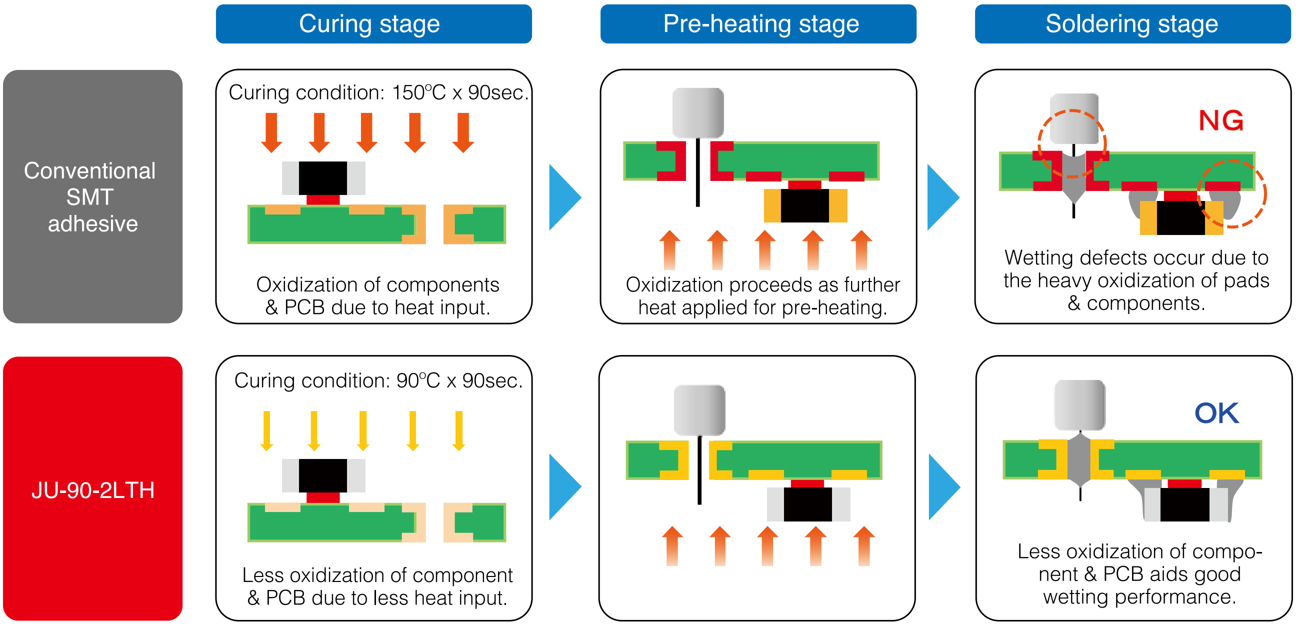
For example;
If the curing temp. is changed from 150°C for 120sec. to 90°C for 120sec…

Electricity consumption : Approx. - 40%
CO_2 emission : Approx. - 70t /year
* Working 365 days x 24hrs x 10lines

Advantage - 2

Prevents components and PCBs prior to the wave soldering process from being destroyed, warped or badly oxidized causing de-wetting defects.

■ Figure 1. Influence of heat damage to components and PCBs



Curing condition: 150°C x 90sec.

Oxidization of components & PCB due to heat input.

Oxidization proceeds as further heat applied for pre-heating.

Wetting defects occur due to the heavy oxidization of pads & components.

Curing condition: 90°C x 90sec.

Less oxidization of component & PCB due to less heat input.

Less oxidization of component & PCB aids good wetting performance.

Product specifications

Product name	**JU-90-2LTH**
Composition	Epoxy
State / Color	Paste / red
Viscosity (Pa.s)	65
Glass transition temperature (°C)	49〜74
Curing conditions	90°C x >90sec.
Shelf life	6 months

Low curing temperature 90°C
Low energy
Stable dispensing
High bonding strength